

preliminary agenda

2017 WIPDA

/ Albuquerque, NM / October 29 – November 01



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Schedule at a Glance: Sunday October 29, 2017

2 PM | 5: 30 PM | ITRW Meeting

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Schedule at a Glance: Monday October 30, 2017

Tutorials are scheduled for 50 minutes with 10-minute breaks following each tutorial.

9 AM	10 AM	Tutorial James Cooper “SiC Power Devices: Physics, Current Status, and Future Trends”
10 AM	11 AM	Tutorial Subhashish Bhattacharya “HV SiC Devices Enabled MV Power Converters Applications and Circuit Topologies – Opportunities and Challenges”
11 AM	12 PM	Tutorial Brij Singh “200 kW, 1050 V _{dc} SiC Dual Inverter for Heavy-Duty Vehicles”
12 PM	2 PM	Lunch
2 P M	3 PM	Tutorial Andrew Lemmon “Special Considerations for Developing Applications for Wide Band-Gap Semiconductors”
3 PM	4 PM	Tutorial Sandeep Bahl “ GaN reliability for Power Devices and Applications ”
4 PM	5 PM	Tutorial Qiang Li “GaN-Based High-Efficiency High-Density Power Converters for Future Data Center”
5 PM	6 PM	Tutorial Eric Persson “ The Pros and Cons of Using GaN HEMTs in PFC Circuit Applications”
6 PM	7:30 PM	Reception

Schedule at a Glance: Tuesday October 31, 2017

8 AM	8:15 AM		Welcome	
8:15 AM	8:45 AM		Keynote #1	
8:45 AM	9:15 AM		Keynote #2	
9:15 AM	9:40 AM		Break	
9:45 AM	10:30 AM		Issues in SiC Panel Session	
10:30 AM	11:15 AM		Issues in GaN Panel Session	
11:15 AM	1:15 PM		Lunch	
1:15 PM	1:45 PM		Keynote #3	
1:45 PM	2:15 PM		Keynote #4	
2:15 PM	2:45 PM		Keynote #5	
2:45 PM	3:15 PM		Break	
3:15 PM	5:20 PM	SiC Inverters / Converters	GaN Technology, Device Optimization, and Reliability	Design and optimization
6 PM	9 PM		Conference Banquet and Poster Session	

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Schedule at a Glance: Wednesday November 1, 2017

8 AM	8:30 AM		Keynote #6	
8:30 AM	9 AM		Keynote #7	
9 AM	9:30 AM		Keynote #8	
9:30 AM	10 AM		Break	
10 AM	11:30 AM	GaN Inverters / Converters	SiC Device/Process Optimization	GaN Characterization
11:30 AM	1 PM		Lunch	
1 PM	2:35 PM	Gate Drivers / Overcurrent Protection	SiC Characterization	Wide Bandgap Packaging and Assembly
2:35 PM	3 PM		Break	
3 PM	4:40 PM	RF / Wireless Power	SiC Reliability	Wide Bandgap Circuit / Assembly Interaction
4:40 PM	5 PM		Wrap-up Session	

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